SCES028G-JULY 1995-REVISED AUGUST 2004

### **FEATURES**

- Member of the Texas Instruments Widebus™
   Family
- EPIC<sup>™</sup> (Enhanced-Performance Implanted CMOS) Submicron Process
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

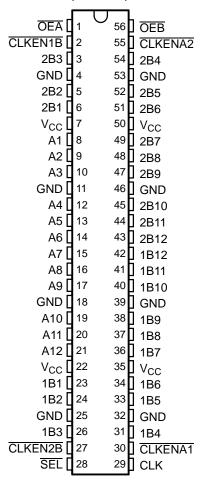
#### DESCRIPTION

This 12-bit to 24-bit registered bus exchanger is designed for 1.65-V to 3.6-V  $V_{\rm CC}$  operation.

The SN74ALVCH16270 is used in applications in which data must be transferred from a narrow high-speed bus to a wide lower-frequency bus.

The device provides synchronous data exchange between the two ports. Data is stored in the internal registers on the low-to-high transition of the clock (CLK) input when the appropriate CLKEN inputs are low. The select (SEL) line selects 1B or 2B data for the A outputs. For data transfer in the A-to-B direction, a two-stage pipeline is provided in the A-to-1B path, with a single storage register in the A-to-2B path. Proper control of the CLKENA inputs allows two sequential 12-bit words to be presented synchronously as a 24-bit word on the B port. Data flow is controlled by the active-low output enables (OEA, OEB). The control terminals are registered to synchronize the bus-direction changes with CLK.

## DGG OR DL PACKAGE (TOP VIEW)



To ensure the high-impedance state during power up or power down, a clock pulse should be applied as soon as possible, and  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver. Due to  $\overline{OE}$  being routed through a register, the active state of the outputs cannot be determined prior to the arrival of the first clock pulse.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16270 is characterized for operation from -40°C to 85°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

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### **FUNCTION TABLES**

### **OUTPUT ENABLE**

	INPUTS		OUTPUTS				
CLK	ŌĒĀ	OEB	Α	1B, 2B			
1	Н	Н	Z	Z			
<b>↑</b>	Н	L	Z	Active			
<b>↑</b>	L	Н	Active	Z			
<b>↑</b>	L	L	Active	Active			

## A-TO-B STORAGE ( $\overline{OEB} = L$ )

				,			
	INPU	ITS		OUTPUTS			
CLKENA1	CLKENA2	CLK	Α	1B	2B		
L	Н	Х	Χ	1B <sub>0</sub> <sup>(1)</sup>	2B <sub>0</sub> <sup>(1)</sup>		
L	Н	X	Х	1B <sub>0</sub> <sup>(1)</sup>	$2B_0^{(1)}$		
L	L	$\uparrow$	L	L <sup>(2)</sup>	L		
L	L	$\uparrow$	Н	H <sup>(2)</sup>	Н		
Н	L	$\uparrow$	L	1B <sub>0</sub> <sup>(1)</sup>	L		
Н	L	$\uparrow$	Н	1B <sub>0</sub> <sup>(1)</sup>	Н		
Н	Н	Χ	Χ	1B <sub>0</sub> <sup>(1)</sup>	2B <sub>0</sub> <sup>(1)</sup>		

<sup>(1)</sup> Output level before the indicated steady-state input conditions were established

(2) Two CLK edges are needed to propagate data.

## B-TO-A STORAGE ( $\overline{OEA} = L$ )

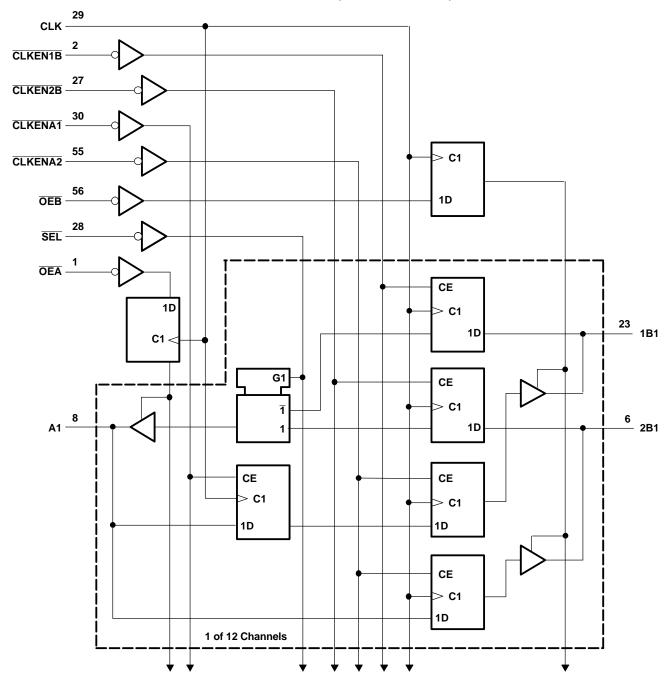
		INP	UTS			OUTPUT
CLKEN1B	CLKEN2B	CLK	SEL	1B	2B	Α
Н	X	Χ	Н	X	X	A <sub>0</sub> <sup>(1)</sup>
X	Н	Χ	L	X	X	A <sub>0</sub> <sup>(1)</sup>
L	X	$\uparrow$	Н	L	X	L
L	X	$\uparrow$	Н	Н	X	н
×	L	$\uparrow$	L	X	L	L
×	L	$\uparrow$	L	X	Н	н

(1) Output level before the indicated steady-state input conditions were established



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### **LOGIC DIAGRAM (POSITIVE LOGIC)**



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### ABSOLUTE MAXIMUM RATINGS(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		-0.5	4.6	V
\ <u></u>	Input voltage range	Except I/O ports <sup>(2)</sup>	-0.5	4.6	V
V <sub>I</sub>	Input voltage range	I/O ports <sup>(2)(3)</sup>	-0.5	V <sub>CC</sub> + 0.5	V
Vo	Output voltage range (2)(3)		-0.5	V <sub>CC</sub> + 0.5	V
I <sub>IK</sub>	Input clamp current	V <sub>1</sub> < 0		-50	mA
I <sub>OK</sub>	Output clamp current	V <sub>O</sub> < 0		-50	mA
Io	Continuous output current			±50	mA
	Continuous current through each V <sub>CC</sub> or G	ND		±100	mA
	Declare thermal impedance (4)	DGG package		81	°C/W
$\theta_{JA}$	Package thermal impedance (4)	DL package		74	-0/00
T <sub>stg</sub>	Storage temperature range		-65	150	°C

<sup>(1)</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

### **RECOMMENDED OPERATING CONDITIONS(1)**

			MIN	MAX	UNIT
V <sub>CC</sub>	Supply voltage		1.65		V
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CC}$		
$V_{IH}$	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		
		V <sub>CC</sub> = 1.65 V to 1.95 V		$0.35 \times V_{CC}$	
$V_{IL}$	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7	V
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8	
V <sub>I</sub>	Input voltage	•	0	V <sub>CC</sub>	V
Vo	Output voltage		0	V <sub>CC</sub>	V
		V <sub>CC</sub> = 1.65 V		-4	
	High lovel output ourrent	V <sub>CC</sub> = 2.3 V		-12	A
I <sub>OH</sub>	High-level output current	V <sub>CC</sub> = 2.7 V		-12	mA
		V <sub>CC</sub> = 3 V		-24	
		V <sub>CC</sub> = 1.65 V		4	
	Law lawal autout aumant	V <sub>CC</sub> = 2.3 V		12	Л
l <sub>OL</sub>	Low-level output current	V <sub>CC</sub> = 2.7 V		12	mA
		V <sub>CC</sub> = 3 V		24	
Δt/Δν	Input transition rise or fall rate	•		10	ns/V
T <sub>A</sub>	Operating free-air temperature		-40	85	°C

<sup>(1)</sup> All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.

<sup>(2)</sup> The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

<sup>3)</sup> This value is limited to 4.6 V maximum.

<sup>(4)</sup> The package thermal impedance is calculated in accordance with JESD 51.



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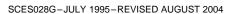
### **ELECTRICAL CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	v <sub>cc</sub>	MIN TYP(1)	MAX	UNIT
	I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2		
	$I_{OH} = -4 \text{ mA}$	1.65 V	1.2		
	$I_{OH} = -6 \text{ mA}$	2.3 V	2		
V <sub>OH</sub>		2.3 V	1.7		V
	I <sub>OH</sub> = -12 mA	2.7 V	2.2		
		3 V	2.4		
	I <sub>OH</sub> = -24 mA	3 V	2		
	$I_{OL} = 100 \mu\text{A}$	1.65 V to 3.6 V		0.2	
	I <sub>OL</sub> = 4 mA	1.65 V		0.45	
\ <u>\</u>	I <sub>OL</sub> = 6 mA	2.3 V		0.4	V
V <sub>OL</sub>	L = 12 mA	2.3 V		0.7	V
	$I_{OL} = 12 \text{ mA}$	2.7 V		0.4	
	I <sub>OL</sub> = 24 mA	3 V		0.55	
I <sub>I</sub>	$V_{I} = V_{CC}$ or GND	3.6 V		±5	μΑ
	$V_1 = 0.58 \text{ V}$	1.65 V	25		
	V <sub>I</sub> = 1.07 V	1.65 V	-25		
	$V_1 = 0.7 \text{ V}$	2.3 V	45		
I <sub>I(hold)</sub>	V <sub>I</sub> = 1.7 V	2.3 V	-45		μΑ
	$V_{I} = 0.8 \text{ V}$	3 V	75		
	$V_1 = 2 V$	3 V	-75		
	$V_1 = 0 \text{ to } 3.6 \text{ V}^{(2)}$	3.6 V		±500	
I <sub>OZ</sub> <sup>(3)</sup>	$V_O = V_{CC}$ or GND	3.6 V		±10	μΑ
I <sub>CC</sub>	$V_I = V_{CC}$ or GND, $I_O = 0$	3.6 V		40	μΑ
Δl <sub>CC</sub>	One input at $V_{CC}$ - 0.6 V, Other inputs at $V_{CC}$ or GND	3 V to 3.6 V		750	μΑ
C <sub>i</sub> Control inputs	$V_{I} = V_{CC}$ or GND	3.3 V	3.5		pF
C <sub>io</sub> A or B ports	$V_O = V_{CC}$ or GND	3.3 V	9		рF

<sup>(1)</sup> All typical values are at  $V_{CC} = 3.3 \text{ V}$ ,  $T_A = 25^{\circ}\text{C}$ . (2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to

For I/O ports, the parameter  $I_{\mbox{\scriptsize OZ}}$  includes the input leakage current.





### **TIMING REQUIREMENTS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

			V <sub>CC</sub> =	1.8 V	V <sub>CC</sub> = ± 0.	2.5 V 2 V	V <sub>CC</sub> =	2.7 V	V <sub>CC</sub> = ± 0.	3.3 V 3 V	UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>clock</sub>	Clock frequency			(1)		150		150		150	MHz
t <sub>w</sub>	Pulse duration, Cl	LK high or low	(1)		3.3		3.3		3.3		ns
		A data before CLK↑	(1)		4.1		3.8		3.1		
		B data before CLK↑	(1)		0.9		1.2		0.9		
t <sub>su</sub>	Setup time	CLKENA1 or CLKENA2 before CLK↑	(1)		3.5		3.2		2.7		ns
		CLKEN1B or CLKEN2B before CLK↑	(1)		3.4		3		2.6		
		OE data before CLK↑	(1)		4.4		3.9		3.2		
		A data after CLK↑	(1)		0		0		0.2		
		B data after CLK↑	(1)		1.4		1		1.7		
t <sub>h</sub>	Hold time	CLKENA1 or CLKENA2 after CLK↑	(1)		0		0.1		0.3		ns
		CLKEN1B or CLKEN2B after CLK↑	(1)		0		0		0.6		
		OE after CLK↑	(1)		0		0		0.1		

<sup>(1)</sup> This information was not available at the time of publication.

### **SWITCHING CHARACTERISTICS**

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM			V <sub>CC</sub> = 1.8 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		2.7 V	V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
	(INPUT)	(OUTPUT)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>			(1)		150		150		150		MHz
	CLK	В		(1)	1.5	5.9		5.8	1.1	5.1	
t <sub>pd</sub>	CLK	A		(1)	1.2	5.4		5.4	1	4.7	ns
	SEL	A		(1)	1.4	6.2		6.4	1	5.5	
t <sub>en</sub>	CLK	A or B		(1)	1.5	7		6.8	1	6	ns
t <sub>dis</sub>	CLK	A or B		(1)	1.9	7.2		6.5	1.1	5.8	ns

<sup>(1)</sup> This information was not available at the time of publication.

### **OPERATING CHARACTERISTICS**

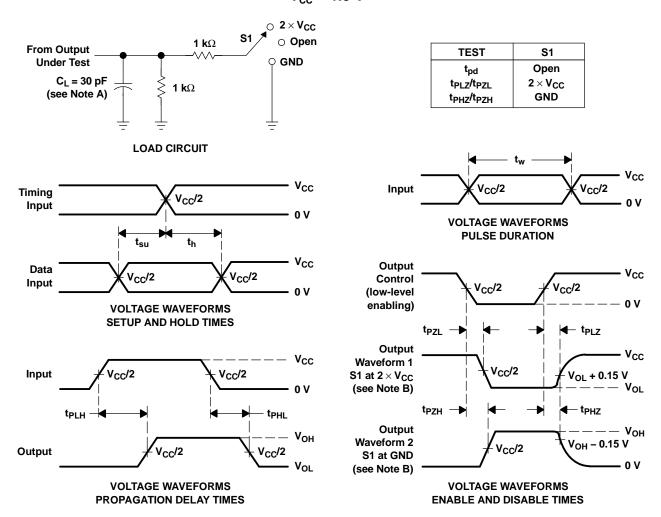
 $T_A = 25^{\circ}C$ 

	PARAMETER		TEST CO	ONDITIONS	V <sub>CC</sub> = 1.8 V	V <sub>CC</sub> = 2.5 V	V <sub>CC</sub> = 3.3 V	UNIT
	Power dissipation	Outputs enabled	C 50 pF	f 40 MHz	(1)	87	120	~F
Cpd	capacitance	Outputs disabled	$C_L = 50 \text{ pF},$	f = 10 MHz	(1)	80.5	118	pF

<sup>(1)</sup> This information was not available at the time of publication.

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# PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V}$

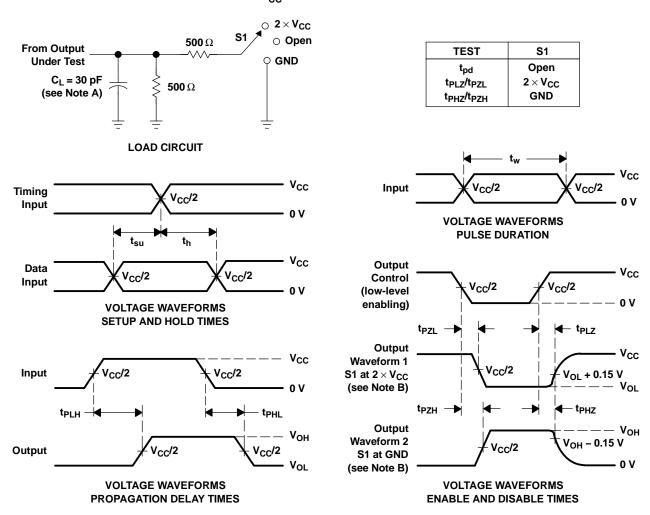


- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z  $_{O}$  = 50  $\Omega,\,t_{f}$   $\leq$  2 ns.  $t_{f}$   $\leq$  2 ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{Pl,7}$  and  $t_{PH7}$  are the same as  $t_{dis}$ .
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms



# PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 2.5 V $\pm$ 0.2 V

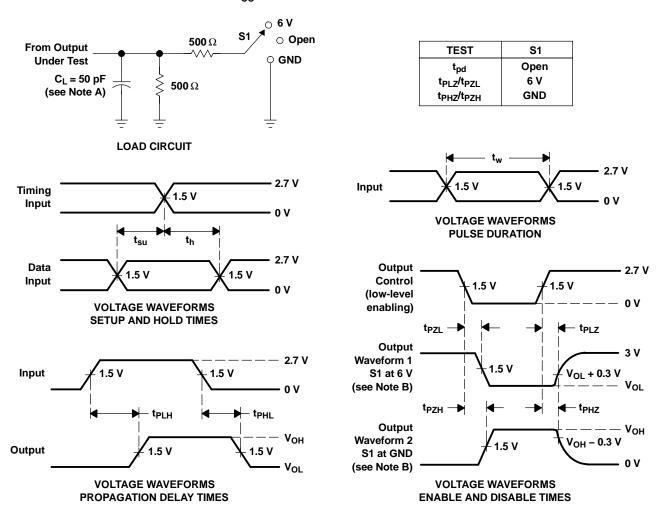


- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z  $_{O}$  = 50  $\Omega,\,t_{f}$   $\leq$  2 ns,  $t_{f}$   $\leq$  2 ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{Pl,7}$  and  $t_{PH7}$  are the same as  $t_{dis}$ .
  - F. t<sub>PZL</sub> and t<sub>PZH</sub> are the same as t<sub>en</sub>.
  - G.  $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 2. Load Circuit and Voltage Waveforms

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# PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 2.7 V AND 3.3 V $\pm$ 0.3 V



- NOTES: A.  $C_L$  includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_0 = 50 \Omega$ ,  $t_r \leq 2.5$  ns.  $t_f \leq 2.5$  ns.
  - D. The outputs are measured one at a time, with one transition per measurement.
  - E.  $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - F.  $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - G. t<sub>PLH</sub> and t<sub>PHL</sub> are the same as t<sub>pd</sub>.

Figure 3. Load Circuit and Voltage Waveforms

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#### PACKAGING INFORMATION

Orderable part number	Status	Material type	Package   Pins	Package qty   Carrier	RoHS	Lead finish/ Ball material	MSL rating/ Peak reflow	Op temp (°C)	Part marking (6)
						(4)	(5)		
SN74ALVCH16270DL	Active	Production	SSOP (DL)   56	20   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16270
SN74ALVCH16270DL.B	Active	Production	SSOP (DL)   56	20   TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16270
SN74ALVCH16270DLR	Active	Production	SSOP (DL)   56	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16270
SN74ALVCH16270DLR.B	Active	Production	SSOP (DL)   56	1000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	ALVCH16270

<sup>(1)</sup> Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

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<sup>(5)</sup> MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

<sup>(6)</sup> Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

## **PACKAGE MATERIALS INFORMATION**

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### TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



#### \*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74ALVCH16270DLR	SSOP	DL	56	1000	330.0	32.4	11.35	18.67	3.1	16.0	32.0	Q1

## **PACKAGE MATERIALS INFORMATION**

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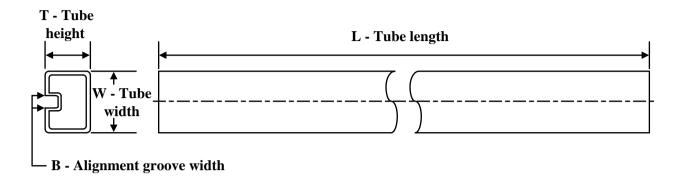
### \*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74ALVCH16270DLR	SSOP	DL	56	1000	367.0	367.0	55.0

## **PACKAGE MATERIALS INFORMATION**

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### **TUBE**



### \*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN74ALVCH16270DL	DL	SSOP	56	20	473.7	14.24	5110	7.87
SN74ALVCH16270DL.B	DL	SSOP	56	20	473.7	14.24	5110	7.87

## DL (R-PDSO-G56)

## PLASTIC SMALL-OUTLINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MO-118

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